TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK2543

### **Switching Regulator Applications**

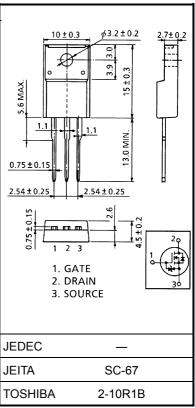
Unit: mm

Low drain-source ON resistance : RDS (ON) = 0.75 Ω (typ.)
 High forward transfer admittance : |Yfs| = 7.0 S (typ.)

• Low leakage current :  $IDSS = 100 \mu A (max) (VDS = 500 V)$ • Enhancement-mode :  $V_{th} = 2.0 \sim 4.0 V (V_{DS} = 10 V, I_D = 1 mA)$ 

### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	500	V	
Drain-gate voltage (Ro	<sub>GS</sub> = 20 kΩ)	$V_{DGR}$	500	V	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1)	I <sub>D</sub>	8	Α	
	Pulse (Note 1)	I <sub>DP</sub>	32	Α	
Drain power dissipation	n (Tc = 25°C)	P <sub>D</sub>	40	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	312	mJ	
Avalanche current		I <sub>AR</sub>	8	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	4	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	



Weight: 1.9 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	3.125	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

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Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 8.3 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 8 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.



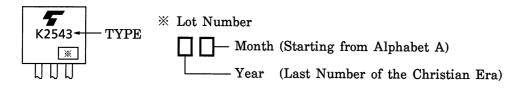
## **Electrical Characteristics (Ta = 25°C)**

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Gate-source bro	eakdown voltage	V (BR) GSS	$I_{G} = \pm 10 \ \mu A, \ V_{GS} = 0 \ V$	±30	_	_	V
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 500 V, V <sub>DS</sub> = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V <sub>(BR) DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	500	_	_	V
Gate threshold v	voltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4 A	_	0.75	0.85	Ω
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 4 A	3.5	7.0	_	S
Input capacitano	e	C <sub>iss</sub>		_	1300	_	
Reverse transfe	r capacitance	C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	130	_	pF
Output capacitance		Coss	]	_	400	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{10 \text{ V}}{\text{O} \text{ V}} \stackrel{\text{I}_{D} = 4 \text{ A}}{\text{O} \text{ V}_{out}} = 50 \Omega$ $V_{DD} = 200 \text{ V}$	_	26	_	
	Turn-on time	t <sub>on</sub>		_	45	-	ns
	Fall time	t <sub>f</sub>		_	40	_	- IIS
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm w} = 10 \mu \rm s$	_	140	_	
Total gate charge (Gate-source plus gate-drain)		Qg	V <sub>DD</sub> ≈ 400 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 8 A		30		
Gate-source charge		Q <sub>gs</sub>		_	17	_	nC
Gate-drain ("miller") charge		$Q_{gd}$			13	_	

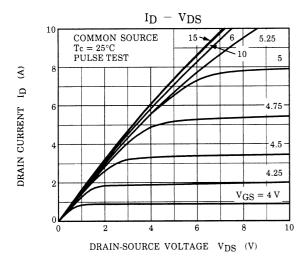
# Source-Drain Ratings and Characteristics (Ta = 25°C)

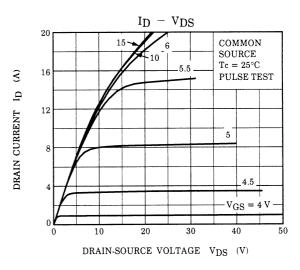
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	8	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	32	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 8 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 8 A, V <sub>GS</sub> = 0 V dI <sub>DR</sub> / dt = 100 A / μs	1	1200	1	ns
Reverse recovery charge	Q <sub>rr</sub>	dl <sub>DR</sub> / dt = 100 A / μs	_	10	_	μC

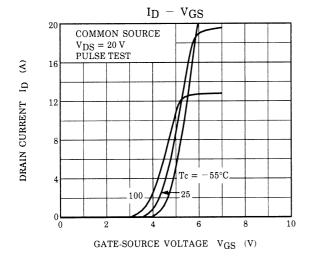
## Marking

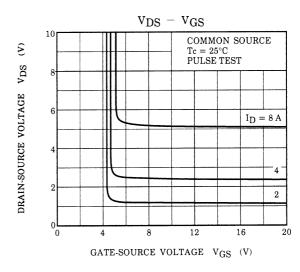


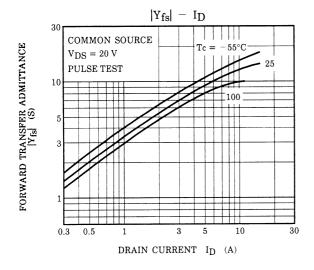
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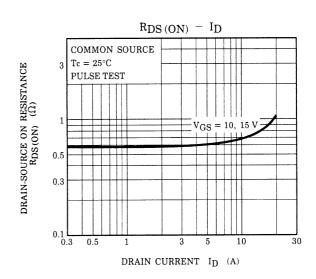




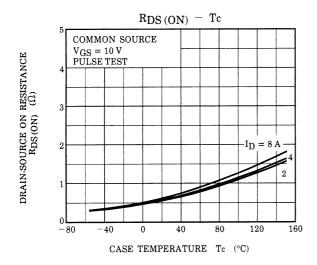


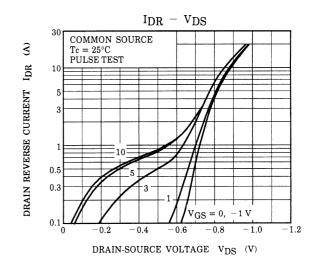


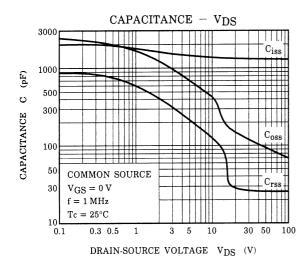


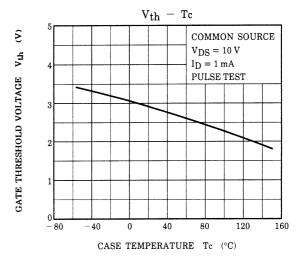


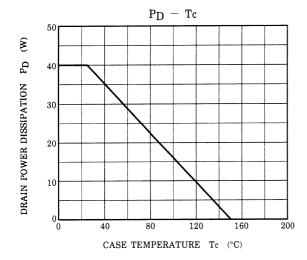
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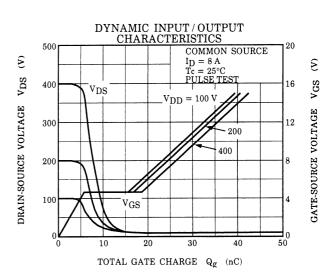




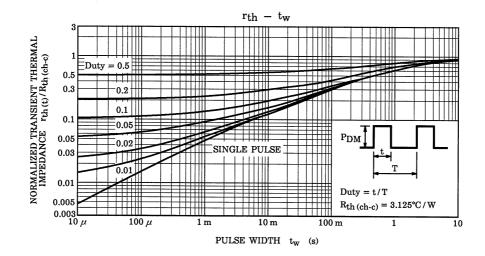


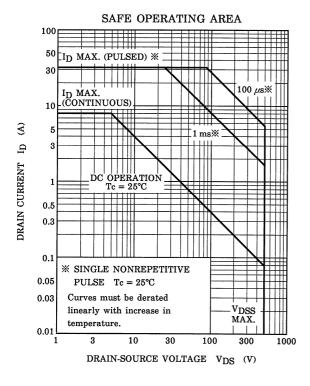


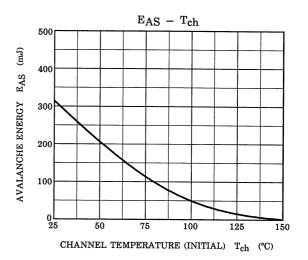


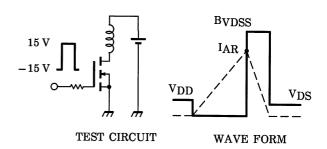


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$$R_G = 25 \Omega$$
  
 $V_{DD} = 90 \text{ V}, L = 8.3 \text{ mH}$   $EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD}\right)$ 

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